


### MG1775S-BN4MM



#### Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E71639

#### Features

- IGBT<sup>3</sup> CHIP(1700V Trench+Field Stop technology)
- Low turn-off losses, short tail current
- $V_{CE(sat)}$  with positive temperature coefficient
- DIODE CHIP(1700V EMCON 3 technology)
- Free wheeling diodes with fast and soft reverse recovery

#### Applications

- High frequency switching application
- Medical applications
- Motion/servo control
- UPS systems

#### Module Characteristics ( $T_c = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Unit
$T_{J(max)}$	Max. Junction Temperature				150	$^\circ\text{C}$
$T_{J(op)}$	Operating Temperature		-40		125	$^\circ\text{C}$
$T_{stg}$	Storage Temperature		-40		125	$^\circ\text{C}$
$V_{isol}$	Insulation Test Voltage	AC, t=1min		4000		V
CTI	Comparative Tracking Index		350			
Torque	Module-to-Sink	Recommended (M6)	3		5	N·m
Torque	Module Electrodes	Recommended (M5)	2.5		5	N·m
Weight				160		g

#### Absolute Maximum Ratings ( $T_c = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Parameters	Test Conditions	Values	Unit
<b>IGBT</b>				
$V_{CES}$	Collector - Emitter Voltage	$T_J=25^\circ\text{C}$	1700	V
$V_{GES}$	Gate - Emitter Voltage		$\pm 20$	V
$I_C$	DC Collector Current	$T_c=25^\circ\text{C}$	125	A
		$T_c=80^\circ\text{C}$	75	A
$I_{CM}$	Repetitive Peak Collector Current	$t_p=1\text{ms}$	150	A
$P_{tot}$	Power Dissipation Per IGBT		520	W
<b>Diode</b>				
$V_{RRM}$	Repetitive Reverse Voltage	$T_J=25^\circ\text{C}$	1700	V
$I_{F(AV)}$	Average Forward Current	$T_c=25^\circ\text{C}$	125	A
		$T_c=80^\circ\text{C}$	75	A
$I_{FRM}$	Repetitive Peak Forward Current	$t_p=1\text{ms}$	150	A
$I^2t$		$T_J=125^\circ\text{C}$ , $t=10\text{ms}$ , $V_R=0\text{V}$	1050	$\text{A}^2\text{S}$

Life Support Note:

#### Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

MG1775S-BN4MM

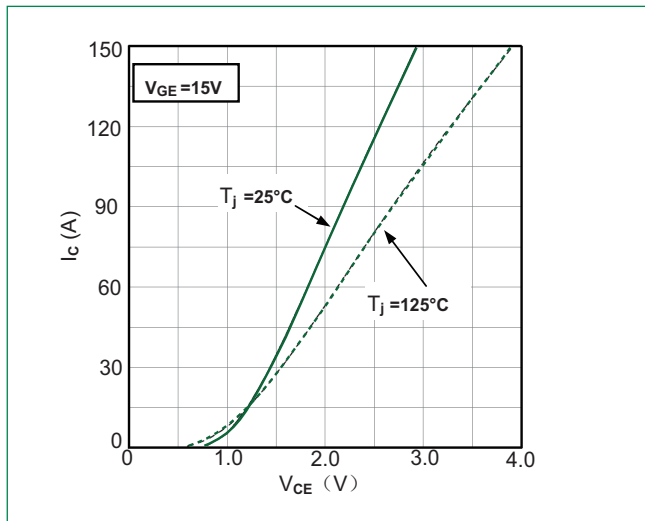
# Power Module

## 1700V 75A IGBT Module

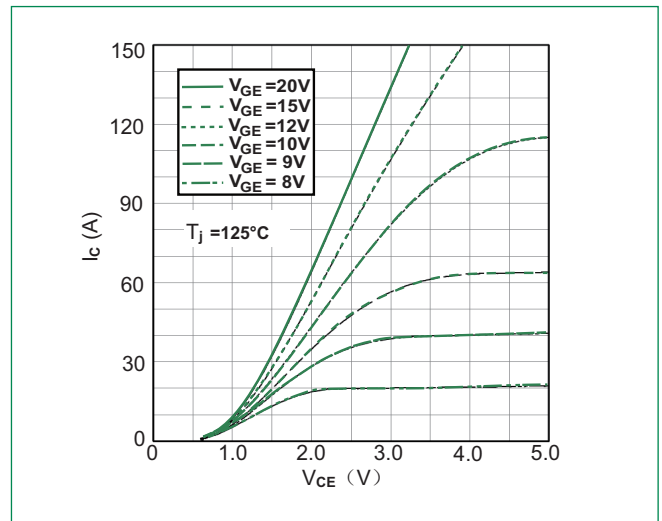
### Electrical and Thermal Specifications ( $T_c = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Parameters	Test Conditions		Min	Typ	Max	Unit
IGBT							
V <sub>GE(th)</sub>	Gate - Emitter Threshold Voltage	V <sub>CE</sub> =V <sub>GE</sub> , I <sub>C</sub> =3.0mA		5.2	5.8	6.4	V
V <sub>CE(sat)</sub>	Collector - Emitter Saturation Voltage	I <sub>C</sub> =75A, V <sub>GE</sub> =15V, T <sub>J</sub> =25°C			2.0	2.45	V
		I <sub>C</sub> =75A, V <sub>GE</sub> =15V, T <sub>J</sub> =125°C			2.4		V
I <sub>CES</sub>	Collector Leakage Current	V <sub>CE</sub> =1700V, V <sub>GE</sub> =0V, T <sub>J</sub> =25°C				3	mA
		V <sub>CE</sub> =1700V, V <sub>GE</sub> =0V, T <sub>J</sub> =125°C				20	mA
I <sub>GES</sub>	Gate Leakage Current	V <sub>CE</sub> =0V, V <sub>GE</sub> =±20V, T <sub>J</sub> =125°C		-400		400	nA
R <sub>Gint</sub>	Intergrated Gate Resistor				8.5		Ω
Q <sub>ge</sub>	Gate Charge	V <sub>CE</sub> =900V, I <sub>C</sub> =75A , V <sub>GE</sub> =±15V			0.9		μC
C <sub>ies</sub>	Input Capacitance	V <sub>CE</sub> =25V, V <sub>GE</sub> =0V, f =1MHz			6.8		nF
C <sub>res</sub>	Reverse Transfer Capacitance				0.22		nF
t <sub>d(on)</sub>	Turn - on Delay Time	V <sub>CC</sub> =900V  I <sub>C</sub> =75A  R <sub>G</sub> =6.8Ω  V <sub>GE</sub> =±15V  Inductive Load	T <sub>J</sub> =25°C		370		ns
			T <sub>J</sub> =125°C		400		ns
t <sub>r</sub>	Rise Time		T <sub>J</sub> =25°C		40		ns
			T <sub>J</sub> =125°C		50		ns
t <sub>d(off)</sub>	Turn - off Delay Time		T <sub>J</sub> =25°C		650		ns
			T <sub>J</sub> =125°C		800		ns
t <sub>f</sub>	Fall Time		T <sub>J</sub> =25°C		180		ns
			T <sub>J</sub> =125°C		300		ns
E <sub>on</sub>	Turn - on Energy		T <sub>J</sub> =25°C		16.5		mJ
			T <sub>J</sub> =125°C		24		mJ
E <sub>off</sub>	Turn - off Energy		T <sub>J</sub> =25°C		16		mJ
			T <sub>J</sub> =125°C		23.5		mJ
I <sub>SC</sub>	Short Circuit Current	t <sub>psc</sub> ≤10μS , V <sub>GE</sub> =15V; T <sub>J</sub> =125°C, V <sub>CC</sub> =1000V			300		A
R <sub>thJC</sub>	Junction-to-Case Thermal Resistance (Per IGBT)					0.24	K/W
Diode							
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> =75A , V <sub>GE</sub> =0V, T <sub>J</sub> =25°C			1.8	2.2	V
		I <sub>F</sub> =75A , V <sub>GE</sub> =0V, T <sub>J</sub> =125°C			1.9		V
I <sub>RRM</sub>	Max. Reverse Recovery Current	I <sub>F</sub> =75A , V <sub>R</sub> =900V  di <sub>F</sub> /dt=-1800A/μs  T <sub>J</sub> =125°C			125		A
Q <sub>rr</sub>	Reverse Recovery Charge				36.5		μC
E <sub>rec</sub>	Reverse Recovery Energy				20.5		mJ
R <sub>thJCD</sub>	Junction-to-Case Thermal Resistance (Per Diode)					0.45	K/W

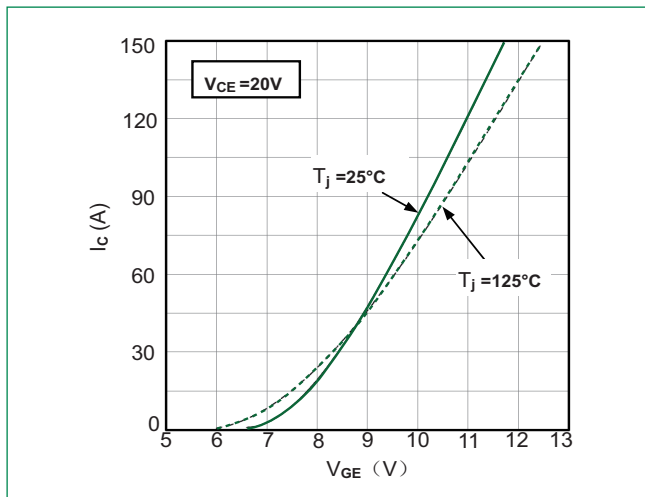
**Figure 1: Typical Output Characteristics**



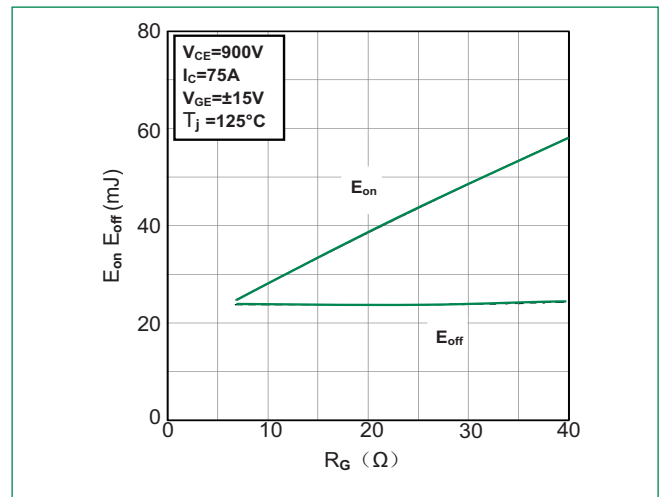
**Figure 2: Typical Output Characteristics**



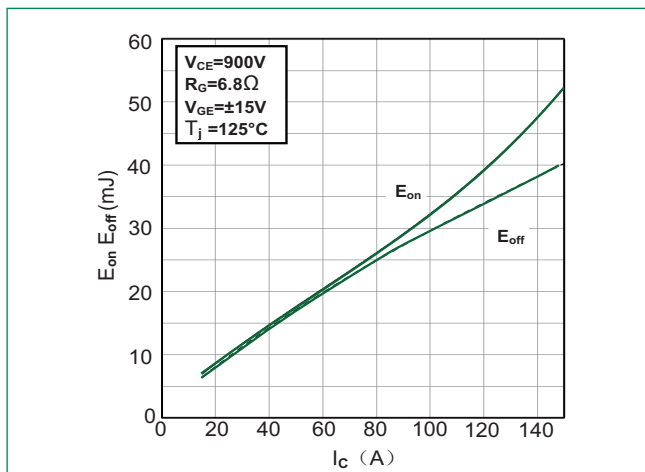
**Figure 3: Typical Transfer characteristics**



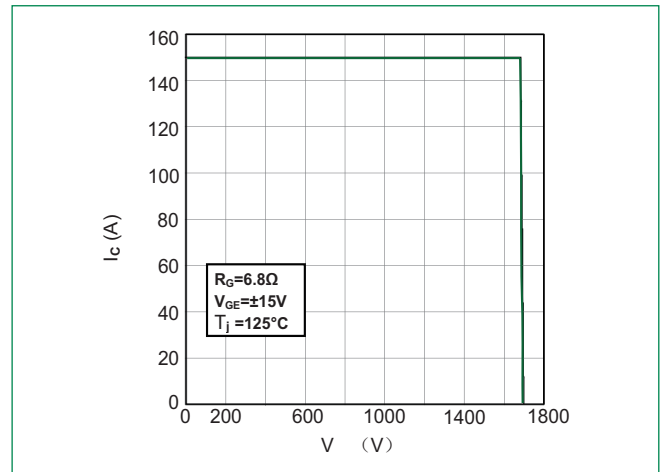
**Figure 4: Switching Energy vs. Gate Resistor**



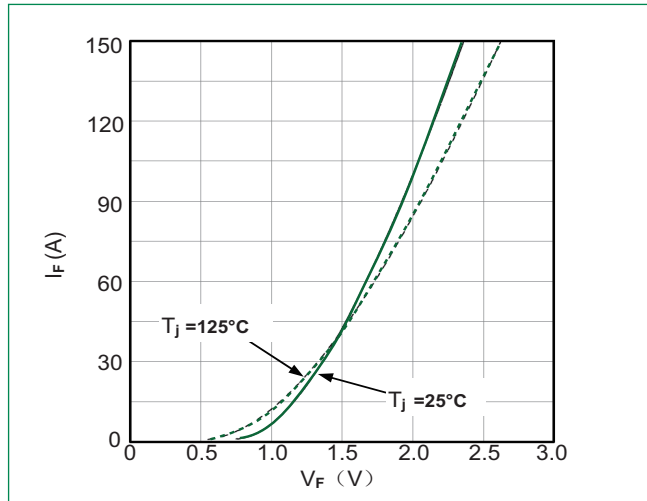
**Figure 5: Switching Energy vs. Collector Current**



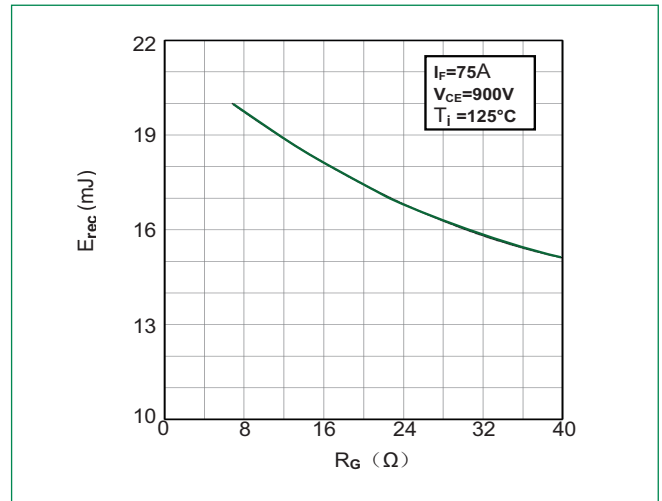
**Figure 6: Reverse Biased Safe Operating Area**



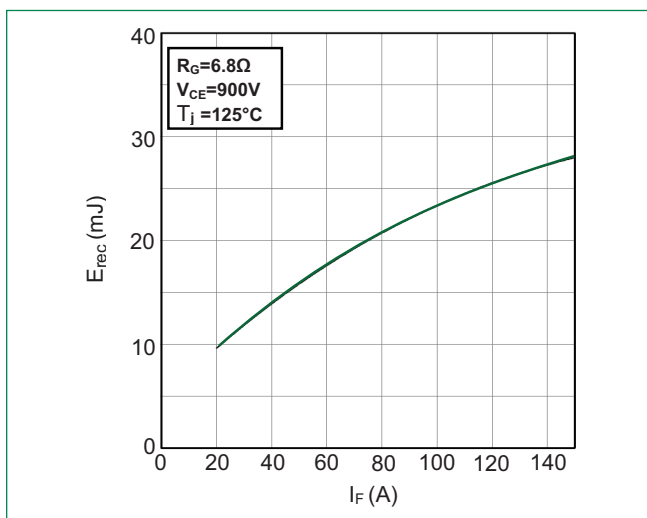
**Figure 7: Diode Forward Characteristics**



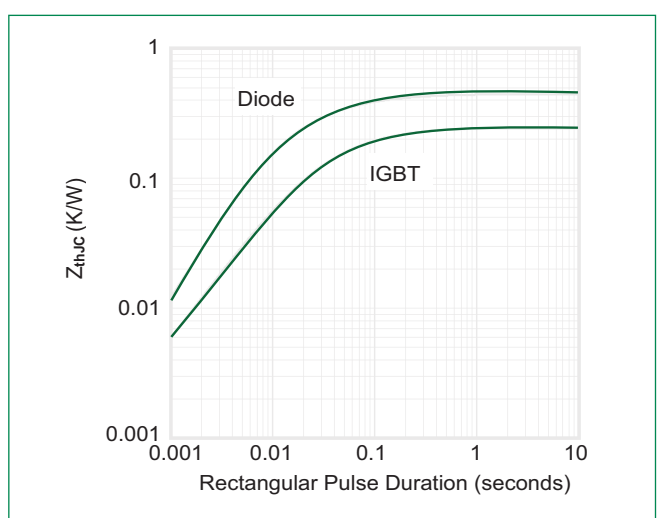
**Figure 8: Switching Energy vs. Gate Resistor**



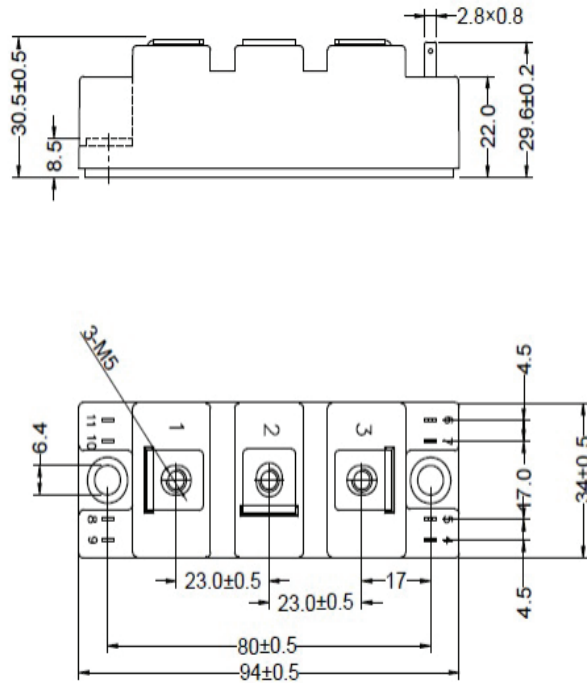
**Figure 9: Switching Energy vs. Forward Current**



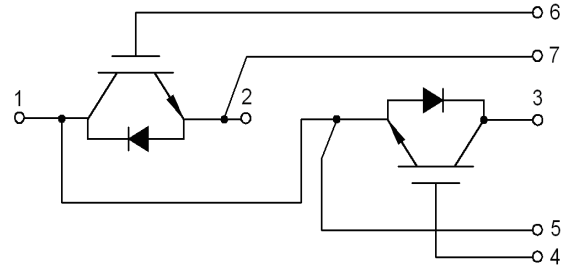
**Figure 10: Transient Thermal Impedance of Diode and IGBT**



### Dimensions-Package S



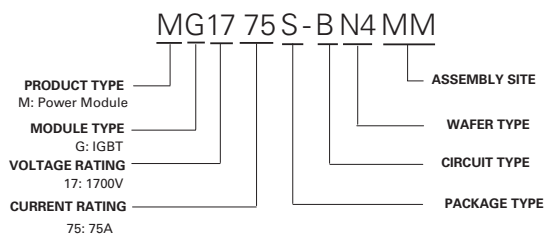
### Circuit Diagram



### Packing Options

Part Number	Marking	Weight	Packing Mode	M.O.Q
MG1775S-BN4MM	MG1775S-BN4MM	160g	Bulk Pack	50

### Part Numbering System



### Part Marking System

